#### Intel - EP4CE10F17C8 Datasheet





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#### Understanding <u>Embedded - FPGAs (Field</u> <u>Programmable Gate Array)</u>

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#### **Applications of Embedded - FPGAs**

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

#### Details

Product Status	Active
Number of LABs/CLBs	645
Number of Logic Elements/Cells	10320
Total RAM Bits	423936
Number of I/O	179
Number of Gates	-
Voltage - Supply	1.15V ~ 1.25V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	256-LBGA
Supplier Device Package	256-FBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep4ce10f17c8

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## Section II. I/O Interfaces

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# 2. Logic Elements and Logic Array Blocks in Cyclone IV Devices

#### CYIV-51002-1.0

This chapter contains feature definitions for logic elements (LEs) and logic array blocks (LABs). Details are provided on how LEs work, how LABs contain groups of LEs, and how LABs interface with the other blocks in Cyclone<sup>®</sup> IV devices.

## **Logic Elements**

Logic elements (LEs) are the smallest units of logic in the Cyclone IV device architecture. LEs are compact and provide advanced features with efficient logic usage. Each LE has the following features:

- A four-input look-up table (LUT), which can implement any function of four variables
- A programmable register
- A carry chain connection
- A register chain connection
- The ability to drive the following interconnects:
  - Local
  - Row
  - Column
  - Register chain
  - Direct link
- Register packing support
- Register feedback support



Figure 3–7 shows a timing waveform for read and write operations in single-port mode with unregistered outputs. Registering the outputs of the RAM simply delays the q output by one clock cycle.



Figure 3–7. Cyclone IV Devices Single-Port Mode Timing Waveform

### **Simple Dual-Port Mode**

Simple dual-port mode supports simultaneous read and write operations to different locations. Figure 3–8 shows the simple dual-port memory configuration.

Figure 3–8. Cyclone IV Devices Simple Dual-Port Memory (1)



#### Note to Figure 3-8:

(1) Simple dual-port RAM supports input or output clock mode in addition to the read or write clock mode shown.

Cyclone IV devices M9K memory blocks support mixed-width configurations, allowing different read and write port widths. Table 3–3 lists mixed-width configurations.

 Table 3–3.
 Cyclone IV Devices M9K Block Mixed-Width Configurations (Simple Dual-Port Mode)
 (Part 1 of 2)

Bood Bort					Write Port				
neau ruit	8192 × 1	4096 × 2	2048 × 4	1024 × 8	512 × 16	256 × 32	1024 × 9	512 × 18	256 × 36
8192 × 1	$\checkmark$	$\checkmark$	$\checkmark$	$\checkmark$	$\checkmark$	$\checkmark$	—	—	_
4096 × 2	$\checkmark$	$\checkmark$	~	$\checkmark$	$\checkmark$	$\checkmark$	—	—	—
2048 × 4	$\checkmark$	$\checkmark$	$\checkmark$	$\checkmark$	$\checkmark$	$\checkmark$	—	—	—
1024 × 8	$\checkmark$	$\checkmark$	$\checkmark$	$\checkmark$	$\checkmark$	$\checkmark$	—	—	—

Figure 5–14 shows a waveform example of the phase relationship of the PLL clocks in this mode.



Figure 5-14. Phase Relationship Between PLL Clocks in Normal Mode

#### Note to Figure 5-14:

(1) The external clock output can lead or lag the PLL internal clock signals.

### **Zero Delay Buffer Mode**

In zero delay buffer (ZDB) mode, the external clock output pin is phase-aligned with the clock input pin for zero delay through the device. When using this mode, use the same I/O standard on the input clock and output clocks to guarantee clock alignment at the input and output pins.

Figure 5–15 shows an example waveform of the phase relationship of the PLL clocks in ZDB mode.





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Altera Corporation

Each Cyclone IV I/O bank has a VREF bus to accommodate voltage-referenced I/O standards. Each VREF pin is the reference source for its  $V_{REF}$  group. If you use a  $V_{REF}$  group for voltage-referenced I/O standards, connect the VREF pin for that group to the appropriate voltage level. If you do not use all the  $V_{REF}$  groups in the I/O bank for voltage-referenced I/O standards, you can use the VREF pin in the unused voltage-referenced groups as regular I/O pins. For example, if you have SSTL-2 Class I input pins in I/O bank 1 and they are all placed in the VREFB1N[0] group, VREFB1N[0] must be powered with 1.25 V, and the remaining VREFB1N[1..3] pins (if available) are used as I/O pins. If multiple  $V_{REF}$  groups are used in the same I/O bank, the VREF pins must all be powered by the same voltage level because the VREF pins are shorted together within the same I/O bank.

- When VREF pins are used as regular I/Os, they have higher pin capacitance than regular user I/O pins. This has an impact on the timing if the pins are used as inputs and outputs.
- **For more information about VREF pin capacitance**, refer to the pin capacitance section in the *Cyclone IV Device Datasheet* chapter.
- For information about how to identify V<sub>REF</sub> groups, refer to the Cyclone IV Device Pin-Out files or the Quartus II Pin Planner tool.

Table 6–4 and Table 6–5 summarize the number of VREF pins in each I/O bank for the Cyclone IV device family.

Table 6-4. Number of VREF Pins Per I/O Bank for Cyclone IV E Devices (Part 1 of 2)

Device		EP4CE6			EP4CE10				EDADE1E	E146E13				EP4CE22			EP4CE30				Er46E40			EP4CE55			EP4CE75		ED APE11E	EL46E113
<b>i/0</b> Bank (1)	144-EQPF	256-UBGA	256-FBGA	144-EQPF	256-UBGA	256-FBGA	144-EQPF	164-MBGA	256-MBGA	256-UBGA	256-FBGA	484-FBGA	144-EQPF	256-UBGA	256-FBGA	324-FBGA	484-FBGA	780-FBGA	324-FBGA	484-UBGA	484-FBGA	780-FBGA	484-UBGA	484-FBGA	780-FBGA	484-UBGA	484-FBGA	780-FBGA	484-FBGA	780-FBGA
1	1	1	1	1	1	1	2	2	2	2	2	2	1	1	1	4	4	4	4	4	4	4	2	2	2	3	3	3	3	3
2	1	1	1	1	1	1	2	2	2	2	2	2	1	1	1	4	4	4	4	4	4	4	2	2	2	3	3	3	3	3
3	1	1	1	1	1	1	2	2	2	2	2	2	1	1	1	4	4	4	4	4	4	4	2	2	2	3	3	3	3	3
4	1	1	1	1	1	1	2	2	2	2	2	2	1	1	1	4	4	4	4	4	4	4	2	2	2	3	3	3	3	3
5	1	1	1	1	1	1	2	2	2	2	2	2	1	1	1	4	4	4	4	4	4	4	2	2	2	3	3	3	3	3
6	1	1	1	1	1	1	2	2	2	2	2	2	1	1	1	4	4	4	4	4	4	4	2	2	2	3	3	3	3	3
7	1	1	1	1	1	1	2	2	2	2	2	2	1	1	1	4	4	4	4	4	4	4	2	2	2	3	3	3	3	3

Differential I/O Standards	I/O Bank Location	External Resistor Network at Transmitter	Transmitter (TX)	Receiver (RX)	
	5,6	Not Required			
	3,4,5,6,7,8	Three Resistors	<b>`</b>	v	
	5,6	Not Required			
RSDS	3,4,7,8	Three Resistors	✓	—	
	3,4,5,6,7,8	Single Resistor			
	5,6	Not Required			
111111-LVD5	3,4,5,6,7,8	Three Resistors	<b>`</b>		
סחמס	5,6	Not Required		_	
FFD3	3,4,5,6,7,8	Three Resistors	<b>`</b>		
BLVDS (1)	3,4,5,6,7,8	Single Resistor	$\checkmark$	$\checkmark$	
LVPECL (2)	3,4,5,6,7,8	—	—	$\checkmark$	
Differential SSTL-2 <sup>(3)</sup>	3,4,5,6,7,8	—	$\checkmark$	$\checkmark$	
Differential SSTL-18 (3)	3,4,5,6,7,8	—	$\checkmark$	$\checkmark$	
Differential HSTL-18 (3)	3,4,5,6,7,8	—	$\checkmark$	$\checkmark$	
Differential HSTL-15 (3)	3,4,5,6,7,8	—	$\checkmark$	$\checkmark$	
Differential HSTL-12 <sup>(3)</sup>	4,5,6,7,8	—	~	$\checkmark$	

Table 6–7. Differential I/O Standards Supported in Cyclone IV GX I/O Banks

#### Notes to Table 6-7:

(1) Transmitter and Receiver  $f_{MAX}$  depend on system topology and performance requirement.

(2) The LVPECL I/O standard is only supported on dedicated clock input pins.

(3) The differential SSTL-2, SSTL-18, HSTL-18, HSTL-15, and HSTL-12 I/O standards are only supported on clock input pins and PLL output clock pins. PLL output clock pins do not support Class II interface type of differential SSTL-18, HSTL-18, HSTL-15, and HSTL-12 I/O standards.

You can use I/O pins and internal logic to implement a high-speed differential interface in Cyclone IV devices. Cyclone IV devices do not contain dedicated serialization or deserialization circuitry. Therefore, shift registers, internal phase-locked loops (PLLs), and I/O cells are used to perform serial-to-parallel conversions on incoming data and parallel-to-serial conversion on outgoing data. The differential interface data serializers and deserializers (SERDES) are automatically constructed in the core logic elements (LEs) with the Quartus II software ALTLVDS megafunction.

#### EN\_ACTIVE\_CLK

The EN\_ACTIVE\_CLK instruction causes the CLKUSR pin signal to replace the internal oscillator as the clock source. When using the EN\_ACTIVE\_CLK instruction, you must enable the internal oscillator for the clock change to occur. After this instruction is issued, other JTAG instructions can be issued while the CLKUSR pin signal remains as the clock source. The clock source is only reverted back to the internal oscillator by issuing the DIS\_ACTIVE\_CLK instruction or a POR.

#### DIS\_ACTIVE\_CLK

The DIS\_ACTIVE\_CLK instruction breaks the CLKUSR enable latch set by the EN\_ACTIVE\_CLK instruction and causes the clock source to revert back to the internal oscillator. After the DIS\_ACTIVE\_CLK instruction is issued, you must continue to clock the CLKUSR pin for 10 clock cycles.

#### **Changing the Start Boot Address of the AP Flash**

In the AP configuration scheme (for Cyclone IV E devices only), you can change the default configuration boot address of the parallel flash memory to any desired address using the APFC\_BOOT\_ADDR JTAG instruction.

#### APFC\_BOOT\_ADDR

The APFC\_BOOT\_ADDR instruction is for Cyclone IV E devices only and allows you to define a start boot address for the parallel flash memory in the AP configuration scheme.

This instruction shifts in a start boot address for the AP flash. When this instruction becomes the active instruction, the TDI and TDO pins are connected through a 22-bit active boot address shift register. The shifted-in boot address bits get loaded into the 22-bit AP boot address update register, which feeds into the AP controller. The content of the AP boot address update register can be captured and shifted-out of the active boot address shift register from TDO.

The boot address in the boot address shift register and update register are shifted to the right (in the LSB direction) by two bits versus the intended boot address. The reason for this is that the two LSB of the address are not accessible. When this boot address is fed into the AP controller, two 0s are attached in the end as LSB, thereby pushing the shifted-in boot address to the left by two bits, which become the actual AP boot address the AP controller gets.

If you have enabled the remote update feature, the APFC\_BOOT\_ADDR instruction sets the boot address for the factory configuration only.

The APFC\_BOOT\_ADDR instruction is retained after reconfiguration while the system board is still powered on. However, you must reprogram the instruction whenever you restart the system board.

- External configuration reset (nCONFIG) assertion
- User watchdog timer time out

Table 8–24 lists the contents of the current state logic in the status register, when the remote system upgrade master state machine is in factory configuration or application configuration accessing the factory information or application information, respectively. The status register bit in Table 8–24 lists the bit positions in a 32-bit logic.

Remote System Upgrade Master State Machine	Status Register Bit	Definition	Description
	31:30	Master state machine current state	The current state of the remote system upgrade master state machine
Factory information (1)	29:24	Reserved bits	Padding bits that are set to all 0's
	23:0	Boot address	The current 24-bit boot address that was used by the configuration scheme as the start address to load the current configuration.
	31:30	Master state machine current state	The current state of the remote system upgrade master state machine
Application information 1 <sup>(2)</sup>	29	User watchdog timer enable bit	The current state of the user watchdog enable, which is active high
	28:0	User watchdog timer time-out value	The current entire 29-bit watchdog time-out value.
	31:30	Master state machine current state	The current state of the remote system upgrade master state machine
Application information 2 <sup>(2)</sup>	29:24	Reserved bits	Padding bits that are set to all 0's
	23:0	Boot address	The current 24-bit boot address that was used as the start address to load the current configuration

<b>Table 8-24.</b>	<b>Remote S</b>	vstem Upgrade	<b>Current State L</b>	oaic Contents I	n Status Regis	ster
		Jotom opgrado		ogio contonto i	n etatae negi	

#### Notes to Table 8-24:

(1) The remote system upgrade master state machine is in factory configuration.

(2) The remote system upgrade master state machine is in application configuration.

The previous two application configurations are available in the previous state registers (previous state register 1 and previous state register 2), but only for debugging purposes.

# **Document Revision History**

Table 10–3 lists the revision history for this chapter.

Table 10–3. Document Revision History

Date	Version	Changes
December 2013	1.3	<ul> <li>Updated the "EXTEST_PULSE" section.</li> </ul>
November 2011	1.0	<ul> <li>Updated the "BST Operation Control" section.</li> </ul>
	1.2	■ Updated Table 10–2.
		<ul> <li>Added Cyclone IV E devices in Table 10–1 and Table 10–2 for the Quartus II software version 9.1 SP1 release.</li> </ul>
February 2010	1.1	■ Updated Figure 10–1 and Figure 10–2.
		<ul> <li>Minor text edits.</li> </ul>
November 2009	1.0	Initial release.

The following describes the 8B/10B encoder behavior in reset condition (as shown in Figure 1–7):

- During reset, the 8B/10B encoder ignores the inputs (tx\_datain and tx\_ctrlenable ports) from the FPGA fabric and outputs the K28.5 pattern from the RD- column continuously until the tx\_digitalreset port is deasserted.
- Upon deassertion of the tx\_digitalreset port, the 8B/10B encoder starts with a negative disparity and transmits three K28.5 code groups for synchronization before it starts encoding and transmitting data on its output.
- Due to some pipelining of the transmitter PCS, some "don't cares" (10'hxxx) are sent before the three synchronizing K28.5 code groups.

clock tx\_digitalreset dataout[9..0] K28.5 K28.5-K28.5 K28.5-. K28.5+ K28.5-Dx.y+ ххх ххх Normal During reset Don't cares after reset Synchronization operation

Figure 1–7. 8B/10B Encoder Behavior in Reset Condition

The encoder supports forcing the running disparity to either positive or negative disparity with tx\_forcedisp and tx\_dispval ports. Figure 1–8 shows an example of tx\_forcedisp and tx\_dispval port use, where data is shown in hexadecimal radix.



Figure 1–8. Force Running Disparity Operation

In this example, a series of K28.5 code groups are continuously sent. The stream alternates between a positive disparity K28.5 (RD+) and a negative disparity K28.5 (RD-) to maintain a neutral overall disparity. The current running disparity at time n + 1 indicates that the K28.5 in time n + 2 should be encoded with a negative disparity. Because tx\_forcedisp is high at time n + 2, and tx\_dispval is low, the K28.5

## **Transmitter Output Buffer**

Figure 1–11 shows the transmitter output buffer block diagram.





#### Note to Figure 1-11:

(1) Receiver detect function is specific for PCIe protocol implementation only. For more information, refer to "PCI Express (PIPE) Mode" on page 1–52.

The Cyclone IV GX transmitter output buffers support the **1.5-V PCML** I/O standard and are powered by VCCH\_GXB power pins with 2.5-V supply. The 2.5-V supply on VCCH\_GXB pins are regulated internally to 1.5-V for the transmitter output buffers. The transmitter output buffers support the following additional features:

- Programmable differential output voltage (V<sub>OD</sub>)—customizes the V<sub>OD</sub> up to 1200 mV to handle different trace lengths, various backplanes, and various receiver requirements.
- Programmable pre-emphasis—boosts high-frequency components in the transmitted signal to maximize the data eye opening at the far-end. The high-frequency components might be attenuated in the transmission media due to data-dependent jitter and intersymbol interference (ISI) effects. The requirement for pre-emphasis increases as the data rates through legacy backplanes increase.
- Programmable differential on-chip termination (OCT)—provides calibrated OCT at differential 100 Ω or 150 Ω with on-chip transmitter common mode voltage (V<sub>CM</sub>) at 0.65 V. V<sub>CM</sub> is tri-stated when you disable the OCT to use external termination.
- Disable OCT to use external termination if the link requires a 85  $\Omega$  termination, such as when you are interfacing with certain PCIe Gen1 or Gen2 capable devices.
- The Cyclone IV GX transmitter output buffers are current-mode drivers. The resulting V<sub>OD</sub> voltage is therefore a function of the transmitter termination value. For lists of supported V<sub>OD</sub> settings, refer to the *Cyclone IV Device Data Sheet*.

The calibration block internally generates a constant internal reference voltage, independent of PVT variations and uses this voltage and the external reference resistor on the RREF pin to generate constant reference currents. The OCT calibration circuit calibrates the OCT resistors present in the transceiver channels. Figure 1–41 shows the calibration block diagram.





#### Notes to Figure 1-41:

- (1) All transceiver channels use the same calibration block clock and power down signals.
- (2) Connect a 2 k $\Omega$  (tolerance max ± 1%) external resistor to the RREF pin to ground. The RREF resistor connection in the board must be free from any external noise.
- (3) Supports up to 125 MHz clock frequency. Use either dedicated global clock or divide-down logic from the FPGA fabric to generate a slow clock on the local clock routing.
- (4) The calibration block restarts the calibration process following deassertion of the cal\_blk\_powerdown signal.

# **PCI-Express Hard IP Block**

Figure 1–42 shows the block diagram of the PCIe hard IP block implementing the PHY MAC, Data Link Layer, and Transaction Layer for PCIe interfaces. The PIPE interface is used as the interface between the transceiver and the hard IP block.

Figure 1–42. PCI Express Hard IP High-Level Block Diagram



Figure 1–59 shows an example of rate match FIFO insertion in the case where one symbol must be inserted. Because the rate match FIFO can only insert /I2/ ordered sets, it inserts one /I2/ ordered set (two symbols inserted).

Figure 1–59. Example of Rate Match FIFO Insertion in GIGE Mode



The rate match FIFO does not insert or delete code groups automatically to overcome FIFO empty or full conditions. In this case, the rate match FIFO asserts the rx\_rmfifofull and rx\_rmfifoempty flags for at least two recovered clock cycles to indicate rate match FIFO full and empty conditions, respectively. You must then assert the rx\_digitalreset signal to reset the receiver PCS blocks.

## **Serial RapidIO Mode**

Serial RapidIO mode provides the non-bonded (×1) transceiver channel datapath configuration for SRIO protocol implementation. The Cyclone IV GX transceiver provides the PMA and the following PCS functions:

- 8B/10B encoding and decoding
- lane synchronization state machine

Cyclone IV GX transceivers do not have built-in support for some PCS functions such as pseudo-random idle sequence generation and lane alignment in ×4 bonded channel configuration. If required, you must implement these functions in a user logics or external circuits.

The RapidIO Trade Association defines a high-performance, packet-switched interconnect standard to pass data and control information between microprocessors, digital signals, communications, network processes, system memories, and peripheral devices. The SRIO physical layer specification defines serial protocol running at 1.25 Gbps, 2.5 Gbps, and 3.125 Gbps in either single-lane (×1) or bonded four-lane (×4) at each line rate. Cyclone IV GX transceivers support single-lane (×1) configuration at all three line rates. Four ×1 channels configured in Serial RapidIO mode can be instantiated to achieve one non-bonded ×4 SRIO link. When implementing four ×1 SRIO channels, the receivers do not have lane alignment or deskew capability.

Block	Port Name	Input/ Output	Clock Domain	Description				
	rx_coreclk	Output	Clock signal	Optional read clock port for the RX phase compensation FIFO.				
RX PCS	rx_phase_comp_fifo _error	Output	Synchronous to tx_clkout (non-bonded modes) or coreclkout (bonded modes)	RX phase compensation FIFO full or empty indicator. <ul> <li>A high level indicates FIFO is either full or empty.</li> </ul>				
	rx_bitslipboundarys electout	Output	Asynchronous signal.	Indicate the number of bits slipped in the word aligner configured in manual alignment mode. Values range from 0 to 9.				
	rx datain	Input	N/A	Receiver serial data input port.				
	rx_freqlocked	Output	Asynchronous signal	<ul> <li>Receiver CDR lock state indicator</li> <li>A high level indicates the CDR is in LTD state.</li> <li>A low level indicates the CDR is in LTR state.</li> </ul>				
RX PMA	rx_locktodata	Input	Asynchronous signal	<ul> <li>Receiver CDR LTD state control signal</li> <li>A high level forces the CDR to LTD state</li> <li>When deasserted, the receiver CDR lock state depends on the rx_locktorefclk signal level.</li> </ul>				
	rx_locktorefclk	Input	Asynchronous signal	<ul> <li>Receiver CDR LTR state control signal.</li> <li>The rx_locktorefclk and rx_locktodata signals control whether the receiver CDR states as follows: <ul> <li>[rx_locktodata:rx_locktorefclk]</li> <li>2'b00—receiver CDR is in automatic lock mode</li> <li>2b'01—receiver CDR is in manual lock mode (LTR state)</li> <li>2b'1x—receiver CDR is in manual lock mode (LTD state)</li> </ul> </li> </ul>				
	rx_signaldetect	Output	Asynchronous signal	<ul> <li>Signal threshold detect indicator.</li> <li>Available in Basic mode when 8B/10B encoder/decoder is used, and in PIPE mode.</li> <li>A high level indicates that the signal present at the receiver input buffer is above the programmed signal detection threshold value.</li> </ul>				
	rx_recovclkout	Output	Clock signal	<ul> <li>CDR low-speed recovered clock</li> <li>Only available in the GIGE mode for applications such as Synchronous Ethernet.</li> </ul>				

Table 1-27	Receiver Ports	in ALTGX Megafunction	for Cyclone IV GX	(Part 3 of 3)
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# **User Reset and Power-Down Signals**

Each transceiver channel in the Cyclone IV GX device has individual reset signals to reset its physical coding sublayer (PCS) and physical medium attachment (PMA). The transceiver block also has a power-down signal that affects the multipurpose phase-locked loops (PLLs), general purpose PLLs, and all the channels in the transceiver block.



Table 2–1 lists the reset signals available for each transceiver channel.

Signal	ALTGX MegaWizard Plug-In Manager Configurations	Description
ty digitalreset (1)	<ul> <li>Transmitter Only</li> <li>Receiver and Transmitter</li> </ul>	Provides asynchronous reset to all digital logic in the transmitter PCS, including the XAUI transmit state machine.
en_argrourrobot		The minimum pulse width for this signal is two parallel clock cycles.
rx_digitalreset <sup>(1)</sup>	<ul> <li>Receiver Only</li> <li>Receiver and Transmitter</li> </ul>	<ul> <li>Resets all digital logic in the receiver PCS, including:</li> <li>XAUI receiver state machines</li> <li>GIGE receiver state machines</li> <li>XAUI channel alignment state machine</li> <li>BIST-PRBS verifier</li> <li>BIST-incremental verifier</li> <li>The minimum pulse width for this signal is two parallel clock evologies</li> </ul>
rx_analogreset	<ul> <li>Receiver Only</li> <li>Receiver and Transmitter</li> </ul>	Resets the receiver CDR present in the receiver channel. The minimum pulse width is two parallel clock cycles.

Table 2–1. Transceiver Channel Reset Signals

#### Note to Table 2–1:

(1) Assert this signal until the clocks coming out of the multipurpose PLL and receiver CDR are stabilized. Stable parallel clocks are essential for proper operation of transmitter and receiver phase-compensation FIFOs in the PCS.

As shown in Figure 2–5, perform the following reset procedure for the receiver CDR in manual lock mode configuration:

- 1. After power up, assert pll areset for a minimum period of 1 µs (the time between markers 1 and 2).
- 2. Keep the tx digitalreset, rx analogreset, rx digitalreset, and rx locktorefclk signals asserted and the rx locktodata signal deasserted during this time period. After you deassert the pll areset signal, the multipurpose PLL starts locking to the input reference clock.
- 3. After the multipurpose PLL locks, as indicated by the pll locked signal going high (marker 3), deassert the tx digitalreset signal (marker 4). For the receiver operation, after deassertion of the busy signal, wait for two parallel clock cycles to deassert the rx\_analogreset signal.
- 4. In a bonded channel group, wait for at least  $t_{LTR\_LTD\_Manual}$ , then deassert rx locktorefclk and assert rx locktodata (marker 7). At this point, the receiver CDR of all the channels enters into lock-to-data mode and starts locking to the received data.
- 5. After asserting the rx locktodata signal, wait for at least t<sub>LTD Manual</sub> before deasserting rx\_digitalreset (the time between markers 7 and 8). At this point, the transmitter and receiver are ready for data traffic.

### Non-Bonded Channel Configuration

In non-bonded channels, each channel in the ALTGX MegaWizard Plug-In Manager instance contains its own tx digitalreset, rx analogreset, rx digitalreset, and rx freqlocked signals.

You can reset each channel independently. For example, if there are four non-bonded channels, the ALTGX MegaWizard Plug-In Manager provides four each of the following signals: tx digitalreset, rx analogreset, rx digitalreset, and rx freqlocked.

Table 2-6 lists the reset and power-down sequences for one channel in a non-bonded configuration under the stated functional modes.

Table 2–6. Reset and Power-Down Sequences for Non-Bonded Channel Configurations							
Channel Set Up	Receiver CDR Mode	Refer to					
Transmitter Only	Basic ×1	"Transmitter Only Channel" on page 2–11					
Receiver Only	Automatic lock mode	"Receiver Only Channel—Receiver CDR in Automatic Lock Mode" on page 2–11					
Receiver Only	Manual lock mode	"Receiver Only Channel—Receiver CDR in Manual Lock Mode" on page 2–12					
Receiver and Transmitter	Automatic lock mode	"Receiver and Transmitter Channel—Receiver CDR in Automatic Lock Mode" on page 2–13					
Receiver and Transmitter	Manual lock mode	"Receiver and Transmitter Channel—Receiver CDR in					

Follow the same reset sequence for all the other channels in the non-bonded configuration.

Manual Lock Mode" on page 2-14

As shown in Figure 2–12, perform the following reset procedure when using the dynamic reconfiguration controller to change the configuration of the transceiver channel:

- After power up and establishing that the transceiver is operating as desired, write the desired new value in the appropriate registers (including reconfig\_mode\_sel[2:0]) and subsequently assert the write\_all signal (marker 1) to initiate the dynamic reconfiguration.
  - **\*** For more information, refer to the *Cyclone IV Dynamic Reconfiguration* chapter.
- 2. Assert the tx\_digitalreset, rx\_analogreset, and rx\_digitalreset signals.
- 3. As soon as write\_all is asserted, the dynamic reconfiguration controller starts to execute its operation. This is indicated by the assertion of the busy signal (marker 2).
- 4. Wait for the assertion of the channel\_reconfig\_done signal (marker 4) that indicates the completion of dynamic reconfiguration in this mode.
- 5. Deassert the tx\_digitalreset signal (marker 5). This signal must be deasserted after assertion of the channel\_reconfig\_done signal (marker 4) and before the deassertion of the rx\_analogreset signal (marker 6).
- 6. Wait for at least five parallel clock cycles after assertion of the channel\_reconfig\_done signal (marker 4) to deassert the rx\_analogreset signal (marker 6).
- Lastly, wait for the rx\_freqlocked signal to go high. After rx\_freqlocked goes high (marker 7), wait for t<sub>LTD\_Auto</sub> to deassert the rx\_digitalreset signal (marker 8). At this point, the receiver is ready for data traffic.

# **Power Down**

The Quartus II software automatically selects the power-down channel feature, which takes effect when you configure the Cyclone IV GX device. All unused transceiver channels and blocks are powered down to reduce overall power consumption. The gxb\_powerdown signal is an optional transceiver block signal. It powers down all transceiver channels and all functional blocks in the transceiver block. The minimum pulse width for this signal is 1 µs. After power up, if you use the gxb\_powerdown signal for a minimum of 1 µs. Lastly, follow the sequence shown in Figure 2–13.

Figure 3–9 shows the connection for PMA reconfiguration mode.



(1) This block can be reconfigured in PMA reconfiguration mode.

### **Transceiver Channel Reconfiguration Mode**

You can dynamically reconfigure the transceiver channel from an existing functional mode to a different functional mode by selecting the **Channel Reconfiguration** option in ALTGX and ALTGX\_RECONFIG MegaWizards. The blocks that are reconfigured by channel reconfiguration mode are the PCS and RX PMA blocks of a transceiver channel.

For more information about reconfiguring the RX PMA blocks of the transceiver channel using channel reconfiguration mode, you can refer to "Data Rate Reconfiguration Mode Using RX Local Divider" on page 3–26.

In channel reconfiguration, only a write transaction can occur; no read transactions are allowed. You can optionally choose to trigger write\_all once by selecting the continuous write operation in the ALTGX\_RECONFIG MegaWizard Plug-In Manager. The Quartus II software then continuously writes all the words required for reconfiguration.

For channel reconfiguration, **.mif** files are required to dynamically reconfigure the transceivers channels in channel reconfiguration modes. The **.mif** carries the reconfiguration information that will be used to reconfigure the transceivers channel dynamically on-the-fly. The **.mif** contents is generated automatically when you select the **Generate GXB Reconfig MIF** option in the Quartus II software setting. For different **.mif** settings, you need to later reconfigure and recompile the ALTGX MegaWizard to generate the **.mif** based on the required reconfiguration settings.

The dynamic reconfiguration controller can optionally perform a continuos write operation or a regular write operation of the **.mif** contents in terms of word size (16-bit data) to the transceivers channel that is selected for reconfiguration.

### Figure 3–9. ALTGX and ALTGX\_RECONFIG Connection for PMA Reconfiguration Mode

I/O V <sub>CC10</sub> (V)			V <sub>REF</sub> (V)	V <sub>TT</sub> (V) <sup>(2)</sup>					
Standard	Min	Тур	Max	Min	lin Typ Max		Min	Тур	Max
SSTL-2 Class I, II	2.375	2.5	2.625	1.19	1.25	1.31	V <sub>REF</sub> – 0.04	V <sub>REF</sub>	V <sub>REF</sub> + 0.04
SSTL-18 Class I, II	1.7	1.8	1.9	0.833	0.9	0.969	V <sub>REF</sub> – 0.04	V <sub>REF</sub>	V <sub>REF</sub> + 0.04
HSTL-18 Class I, II	1.71	1.8	1.89	0.85	0.9	0.95	0.85	0.9	0.95
HSTL-15 Class I, II	1.425	1.5	1.575	0.71	0.75	0.79	0.71	0.75	0.79
HSTL-12	HSTL-12 1 14	1 1/ 1 2	1.2 1.26	0.48 x V <sub>CCI0</sub> <i>(3)</i>	0.5 x V <sub>CCIO</sub> <i>(3)</i>	0.52 x V <sub>CCIO</sub> <i>(3)</i>		0.5 x	
Class I, II	1.14	1.2	1.20	0.47 x V <sub>CCI0</sub> (4)	0.5 x V <sub>CCIO</sub> <sup>(4)</sup>	0.53 x V <sub>CCI0</sub> (4)		V <sub>CCIO</sub>	

Table 1–16.	Single-Ended SSTL and HSTL I/O Reference	Voltage Sr	pecifications for C	vclone IV Devices <sup>(1)</sup>
		· · · · · · · · · · · · · · · · · · ·	voonnoutions ioi e	yolollo IY Borloos

#### Notes to Table 1–16:

(1) For an explanation of terms used in Table 1–16, refer to "Glossary" on page 1–37.

(2)  $\,\,V_{TT}$  of the transmitting device must track  $V_{REF}$  of the receiving device.

(3) Value shown refers to DC input reference voltage,  $V_{\text{REF(DC)}}.$ 

(4) Value shown refers to AC input reference voltage,  $V_{\text{REF(AC)}}$ .

Table 1–17.	Single-Ended SSTL	and HSTL I/O Standards Si	gnal Specifications for C	yclone IV Devices
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I/O	I/O V <sub>IL(DC)</sub> (V) V <sub>IH(DC)</sub> (V)		V <sub>IL(AC)</sub> (V) V <sub>IH(</sub> ,		<sub>(AC)</sub> (V)	V <sub>OL</sub> (V)	V <sub>oh</sub> (V)	I <sub>OL</sub>	I <sub>oh</sub>			
Standard	Min	Max	Min	Max	Min	Max	Min	Max	Max	Min	(mĀ)	(mÄ)
SSTL-2 Class I	_	V <sub>REF</sub> – 0.18	V <sub>REF</sub> + 0.18	_	_	V <sub>REF</sub> – 0.35	V <sub>REF</sub> + 0.35	—	V <sub>TT</sub> – 0.57	V <sub>TT</sub> + 0.57	8.1	-8.1
SSTL-2 Class II	_	V <sub>REF</sub> – 0.18	V <sub>REF</sub> + 0.18	_	_	V <sub>REF</sub> – 0.35	V <sub>REF</sub> + 0.35	_	V <sub>Π</sub> – 0.76	V <sub>TT</sub> + 0.76	16.4	-16.4
SSTL-18 Class I	_	V <sub>REF</sub> – 0.125	V <sub>REF</sub> + 0.125	_	_	V <sub>REF</sub> – 0.25	V <sub>REF</sub> + 0.25	—	V <sub>TT</sub> – 0.475	V <sub>TT</sub> + 0.475	6.7	-6.7
SSTL-18 Class II	_	V <sub>REF</sub> – 0.125	V <sub>REF</sub> + 0.125	_	_	V <sub>REF</sub> – 0.25	V <sub>REF</sub> + 0.25	—	0.28	V <sub>CCI0</sub> – 0.28	13.4	-13.4
HSTL-18 Class I	_	V <sub>REF</sub> – 0.1	V <sub>REF</sub> + 0.1	_	_	V <sub>REF</sub> – 0.2	V <sub>REF</sub> + 0.2	—	0.4	V <sub>CCIO</sub> – 0.4	8	-8
HSTL-18 Class II	_	V <sub>REF</sub> – 0.1	V <sub>REF</sub> + 0.1	_	_	V <sub>REF</sub> – 0.2	V <sub>REF</sub> + 0.2	_	0.4	V <sub>CCI0</sub> – 0.4	16	-16
HSTL-15 Class I	_	V <sub>REF</sub> – 0.1	V <sub>REF</sub> + 0.1	_	_	V <sub>REF</sub> – 0.2	V <sub>REF</sub> + 0.2	_	0.4	V <sub>CCI0</sub> – 0.4	8	-8
HSTL-15 Class II	_	V <sub>REF</sub> – 0.1	V <sub>REF</sub> + 0.1	_	_	V <sub>REF</sub> – 0.2	V <sub>REF</sub> + 0.2	_	0.4	V <sub>CCI0</sub> – 0.4	16	-16
HSTL-12 Class I	-0.15	V <sub>REF</sub> - 0.08	V <sub>REF</sub> + 0.08	V <sub>CCI0</sub> + 0.15	-0.24	V <sub>REF</sub> – 0.15	V <sub>REF</sub> + 0.15	V <sub>CCI0</sub> + 0.24	0.25 × V <sub>CCI0</sub>	0.75 × V <sub>CCIO</sub>	8	-8
HSTL-12 Class II	-0.15	V <sub>REF</sub> - 0.08	V <sub>REF</sub> + 0.08	V <sub>CCI0</sub> + 0.15	-0.24	V <sub>REF</sub> – 0.15	V <sub>REF</sub> + 0.15	V <sub>CCI0</sub> + 0.24	0.25 × V <sub>CCI0</sub>	0.75 × V <sub>CCIO</sub>	14	-14

### Table 1-47. Document Revision History

Date	Version	Changes
February 2010	1.1	<ul> <li>Updated Table 1–3 through Table 1–44 to include information for Cyclone IV E devices and Cyclone IV GX devices for Quartus II software version 9.1 SP1 release.</li> <li>Minor text edits.</li> </ul>
November 2009	1.0	Initial release.